Amendments to the Claims

The listing of claims replaces the previous version, and the listing of claims:

Listing of Claims

1. (currently amended) A plasma-enhanced processing apparatus, comprising;

a process chamber for processing a substrate therein having a wall,

a pumping system communicating with said process chamber for exhausting gas in the process chamber,

a gas-introduction system that introduces process gas into said process chamber,

plasma-generation means that generates plasma in said process chamber by applying energy to said process gas,

a substrate holder that holds said substrate in said process chamber, and

an opposite electrode disposed in the process chamber to face said substrate held by said substrate holder, and including a front board facing the substrate holder, a clamping plate disposed at a front side of the front board close to the substrate holder so that an area of the front board not covered by the clamping plate is exposed to plasma, and a main body installed on the wall of the process chamber and disposed at a back side of the front board opposite to the front side so that said front board is ~~sandwiched~~ clamped between the clamping plate and the main body ~~without a screw~~, said clamping plate being fixed so that said clamping plate presses said front board toward said main body and a back surface of the front board is contacted and pressed uniformly onto the main body, said front board being fixed to said main body by pressure of said clamping plate toward said main body with no screw penetrating said front board ~~said clamping plate contacting a front surface of~~

~~the front board and pressing the front board toward the main body so that a back surface of the front board is contacted and pressed uniformly onto the main body~~.

2. (previously presented) A plasma-enhanced processing apparatus as claimed in claim 1, wherein said opposite electrode includes a cooling mechanism that cools said front board via said main body.

3. (previously presented) A plasma-enhanced processing apparatus as claimed in claim 1, wherein said clamping plate is in surface contact with said front board to clamp a periphery of the front board.

4. (previously presented) A plasma-enhanced processing apparatus as claimed in claim 3, wherein said front board has a stepped portion at said periphery that is sandwiched by said main body and said clamping plate, and a front surface of said clamping plate exposed to the plasma is on a same plane as the front surface of the front board.

5. (previously presented) A plasma-enhanced processing apparatus as claimed in claim 1, further comprising a protector covering a front surface of said clamping plate so that said front surface of the clamping plate is not exposed to said plasma.

6. (previously presented) A plasma-enhanced processing apparatus as claimed in claim 5, wherein said front board has a stepped portion at a periphery sandwiched by the main body and the clamping plate, a back surface of a protector contacting the front surface of the clamping plate, and a front surface of the protector is on a same plane as the front surface of said front board.

7. (previously presented) A plasma-enhanced processing apparatus as claimed in claim 6, wherein said front board is made of silicon poly-crystal or silicon mono-crystal.

8. (previously presented) A plasma-enhanced processing apparatus as claimed in claim 3, wherein said clamping plate is screwed on a member except said front board to press said front board onto said main body with screwing torque of 1Nm or more.

9. (previously presented) A plasma-enhanced processing apparatus as claimed in claim 6, wherein said clamping plate is screwed on a member except said front board to press said front board onto said main body with screwing torque of 1Nm or more.

10. (previously presented) A plasma-enhanced processing apparatus as claimed in claim 6, further comprising a sheet made of carbon inserted between said main body and said front board.

11. (cancelled)

12. (previously presented) A plasma-enhanced processing apparatus as claimed in claim 1, further comprising a sheet between the main body and the front board.

13. (previously presented) A plasma-enhanced processing apparatus as claimed in claim 12, wherein said sheet is made of carbon.

14. (previously presented) A plasma-enhanced processing apparatus as claimed in claim 2, wherein said cooling mechanism prevents increase of temperature of the front board in operation.

15. (currently amended) A plasma-enhanced processing apparatus as claimed in claim ~~1~~ 4, wherein said opposite electrode further includes an insulation casing disposed around the main body, and said clamping plate is fixed to the insulation casing at the stepped portion thereof.

16. (previously presented) A plasma-enhanced processing apparatus as claimed in claim 15, further comprising a screw for fixing the clamping plate to the insulation casing at the stepped portion thereof.

17. (previously presented) A plasma-enhanced processing apparatus as claimed in claim 16, further comprising an L-shaped protector covering the screw and at least a part of the clamping plate, said L-shaped protector being fixed to the insulation casing at a side thereof.

18. (new) A plasma-enhanced processing apparatus as claimed in claim 1, wherein said clamping plate is attached to the opposite electrode by screws which do not contact the front board.